



DOCKET: CU-2417

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Takahiro IIJIMA et al.]

Serial No.: 09/736,864]

Filed: December 14, 2000]

For: INTERCONNECTION SUBSTRATE]
HAVING METAL COLUMNS COVERED BY A]
RESIN FILM AND MANUFACTURING]
METHOD THEREOF]

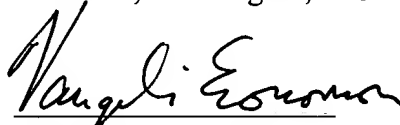
GRP ART UNIT : 2815

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Certification under 37 C.F.R. §1.8(a)

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Commissioner for Patents, Washington, D.C. 20231 on January 30, 2003.


Vangelis Economou

Commissioner for Patents
Washington, D.C. 20231

RETRANSMITTAL OF CORRECTED DRAWINGS
FOR EXAMINER'S APPROVAL

Sir:

Attached please find copies of drawing Fig. 2A (1 sheet), indicating by red ink the drawing correction for which the approval of the Examiner is respectfully requested. The drawing corrections have been requested by the Examiner in the Official Action dated June 25, 2002, and were disapproved when earlier submitted.

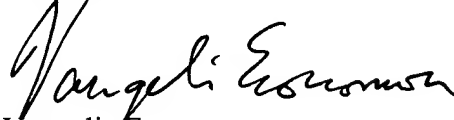
The identical changes have been made in respect of drawing Fig. 2A, that is, the lead line for the electrode 107 has been extended to indicate the correct element.

*Fig 10 Drawing
Changes*

*2/12/03
Shm th*

No new matter has been added to the drawings. The drawing figures are substantively identical to the drawings filed with the original application documents.

Respectfully submitted,



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January 30, 2003

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